



**THE DATASHEET OF  
VU052-12NO1**



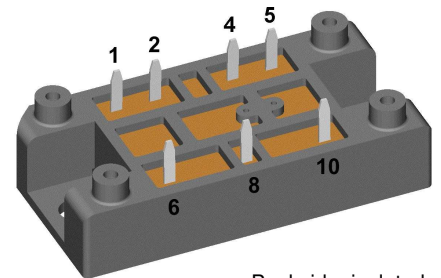
# Standard Rectifier Module

<b>3~ Rectifier</b>	
$V_{RRM} =$	1200 V
$I_{DAV} =$	60 A
$I_{FSM} =$	350 A

## 3~ Rectifier Bridge

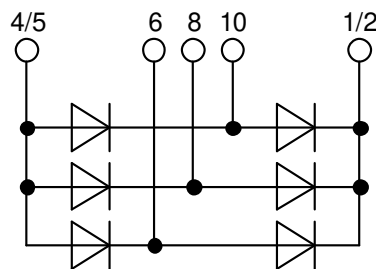
**Part number**

**VUO52-12NO1**



Backside: isolated

E72873



### Features / Advantages:

- Package with DCB ceramic
- Improved temperature and power cycling
- Planar passivated chips
- Very low forward voltage drop
- Very low leakage current

### Applications:

- Diode for main rectification
- For three phase bridge configurations
- Supplies for DC power equipment
- Input rectifiers for PWM inverter
- Battery DC power supplies
- Field supply for DC motors

### Package: V1-A-Pack

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Height: 17 mm
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

### Terms and Conditions of Usage

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office.

Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend

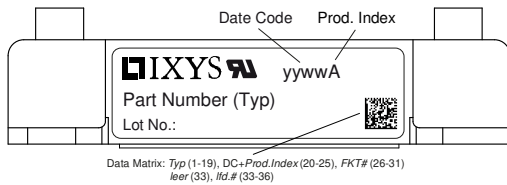
- to perform joint risk and quality assessments;

- the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

Rectifier				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
$V_{RSM}$	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^{\circ}C$			1300	V	
$V_{RRM}$	max. repetitive reverse blocking voltage	$T_{VJ} = 25^{\circ}C$			1200	V	
$I_R$	reverse current	$V_R = 1200\text{ V}$	$T_{VJ} = 25^{\circ}C$		40	$\mu A$	
		$V_R = 1200\text{ V}$	$T_{VJ} = 150^{\circ}C$		1.5	mA	
$V_F$	forward voltage drop	$I_F = 20\text{ A}$	$T_{VJ} = 25^{\circ}C$		1.13	V	
		$I_F = 60\text{ A}$			1.44	V	
		$I_F = 20\text{ A}$	$T_{VJ} = 125^{\circ}C$		1.07	V	
		$I_F = 60\text{ A}$			1.50	V	
$I_{DAV}$	bridge output current	$T_C = 110^{\circ}C$ rectangular $d = \frac{1}{3}$	$T_{VJ} = 150^{\circ}C$		60	A	
$V_{FO}$	threshold voltage	} for power loss calculation only	$T_{VJ} = 150^{\circ}C$		0.83	V	
$r_F$	slope resistance				11.5	m $\Omega$	
$R_{thJC}$	thermal resistance junction to case				1.3	K/W	
$R_{thCH}$	thermal resistance case to heatsink			0.3		K/W	
$P_{tot}$	total power dissipation		$T_C = 25^{\circ}C$		95	W	
$I_{FSM}$	max. forward surge current	$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 45^{\circ}C$		350	A	
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$		380	A	
		$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 150^{\circ}C$		300	A	
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$		320	A	
$I^2t$	value for fusing	$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 45^{\circ}C$		615	A <sup>2</sup> s	
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$		600	A <sup>2</sup> s	
		$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 150^{\circ}C$		450	A <sup>2</sup> s	
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$		425	A <sup>2</sup> s	
$C_J$	junction capacitance	$V_R = 400\text{ V}; f = 1\text{ MHz}$	$T_{VJ} = 25^{\circ}C$		10	pF	

Package V1-A-Pack				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
$I_{RMS}$	RMS current	per terminal			100	A	
$T_{VJ}$	virtual junction temperature		-40		150	°C	
$T_{op}$	operation temperature		-40		125	°C	
$T_{stg}$	storage temperature		-40		125	°C	
<b>Weight</b>					37	g	
$M_D$	mounting torque		2		2.5	Nm	
$d_{Spp/ App}$	creepage distance on surface / striking distance through air	terminal to terminal	6.0			mm	
$d_{Spb/ Apb}$		terminal to backside	12.0			mm	
$V_{ISOL}$	isolation voltage	t = 1 second	3600			V	
		t = 1 minute	3000			V	



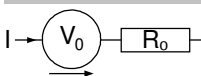
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	VUO52-12NO1	VUO52-12NO1	Blister	24	461172

Similar Part	Package	Voltage class
VUO52-08NO1	V1-A-Pack	800
VUO52-14NO1	V1-A-Pack	1400
VUO52-16NO1	V1-A-Pack	1600
VUO52-18NO1	V1-A-Pack	1800
VUO52-20NO1	V1-A-Pack	2000
VUO52-22NO1	V1-A-Pack	2200
VUO34-16NO1	V1-A-Pack	1600
VUO34-18NO1	V1-A-Pack	1800

### Equivalent Circuits for Simulation

\* on die level

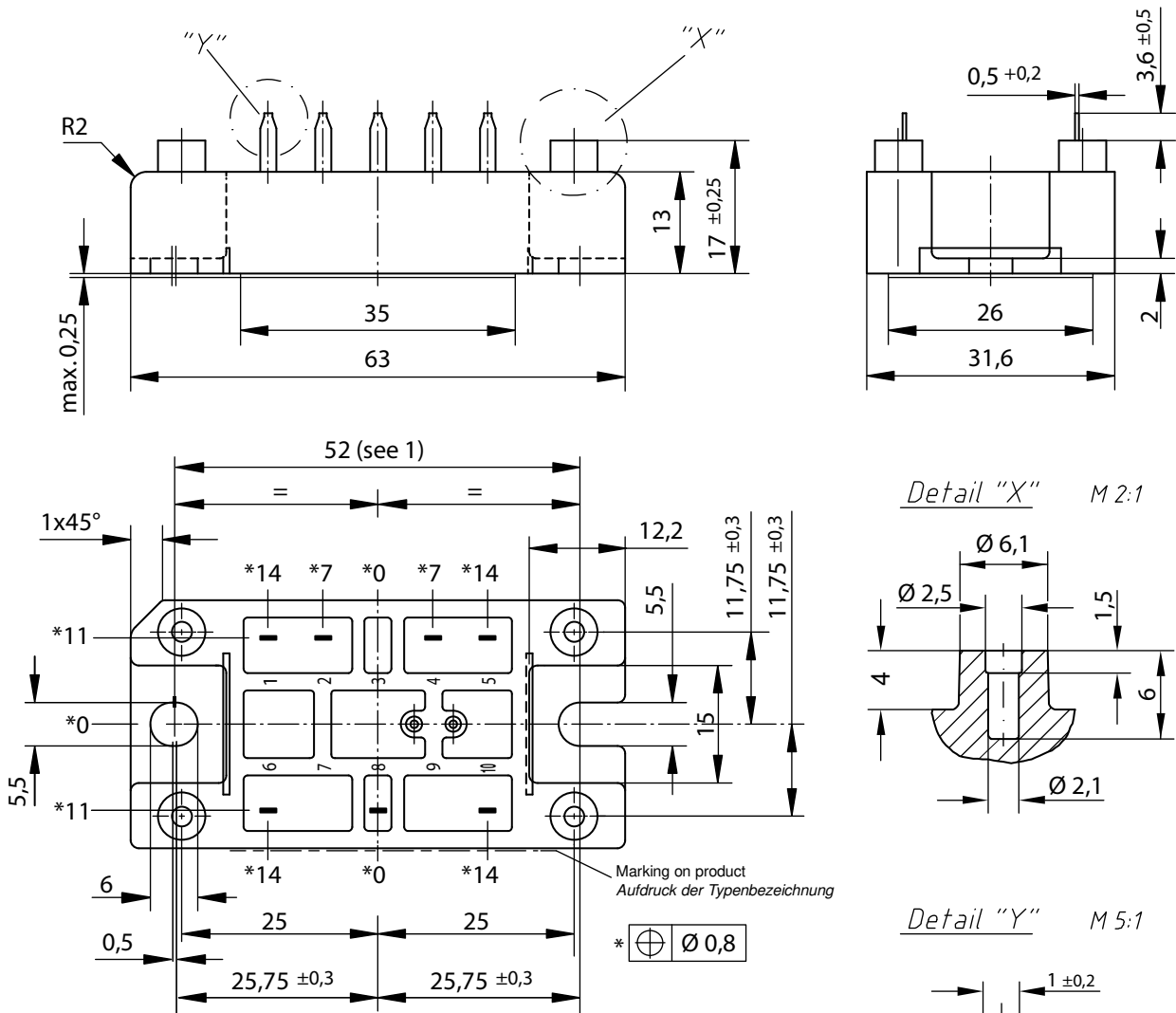
$T_{VJ} = 150\text{ °C}$



**Rectifier**

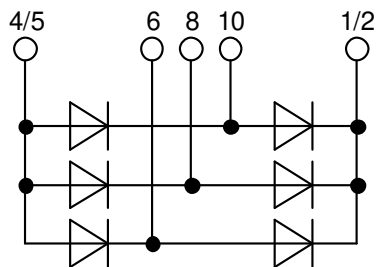
$V_{0\ max}$	threshold voltage	0.83	V
$R_{0\ max}$	slope resistance *	10.2	mΩ

## Outlines V1-A-Pack



### Remarks / Bemerkungen:

1. Nominal distance mounting screws on heat sink: 52 mm / Nennabstand Befestigungsschrauben auf Kühlkörper: 52 mm
  2. General tolerance / Allgemeintoleranz: DIN ISO 2768 -T1-c
  3. Surface treatment of pins: tin plated (Sn) in hot dip / Oberflächenbehandlung der Pins: verzinkt (Sn) im Tauchbad
  4. Detail X: EJOPT® self-tapping screws (dimension K25) to be recommended for mounting on PCB  
selbstschneidende Schraube (Größe K25) empfohlen für die PCB-Montage
- Take care on the maximum screw length according to board thickness and the maximum hole depth of 6 mm<sup>L</sup>  
Bei der Wahl der Schraubenlänge die PCB-Dicke und die maximale Lochtiefe von 6mm beachten
- Recommended mounting torque: 1.5 Nm / Empfohlenes Drehmoment: 1.5 Nm



Rectifier

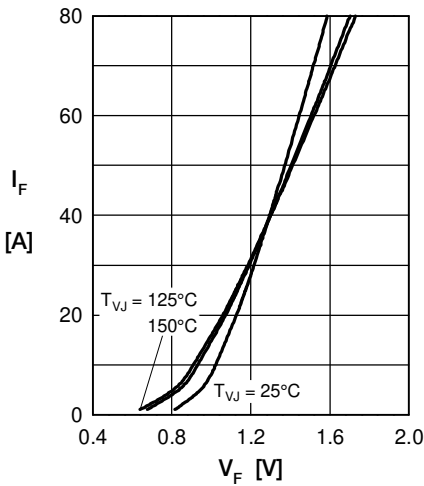


Fig. 1 Forward current vs. voltage drop per diode

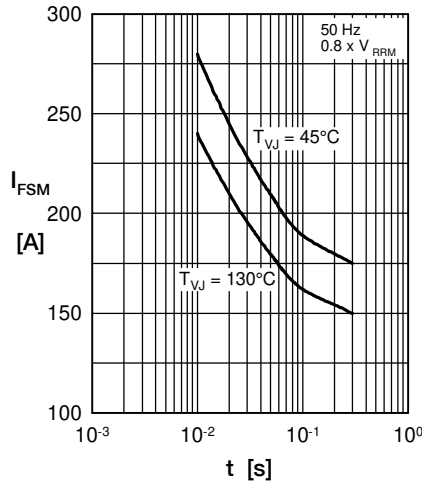


Fig. 2 Surge overload current vs. time per diode

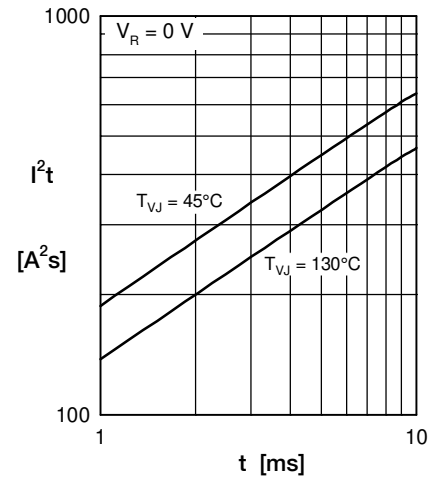


Fig. 3  $I^2t$  vs. time per diode

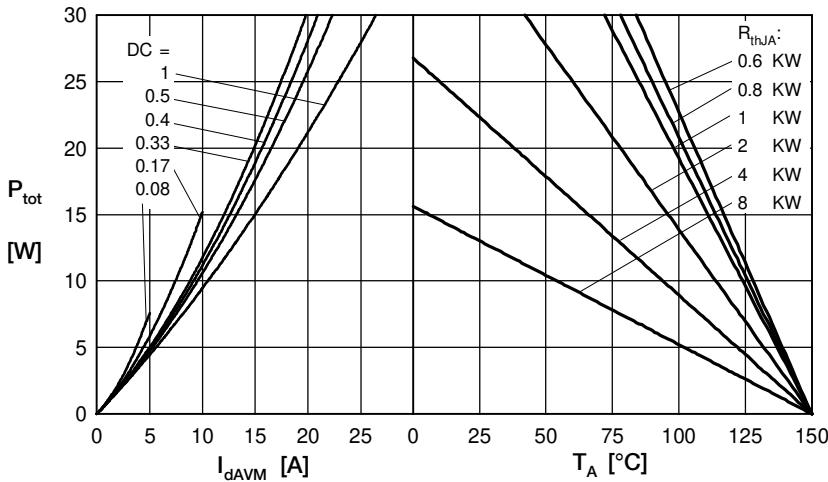


Fig. 4 Power dissipation vs. forward current and ambient temperature per diode

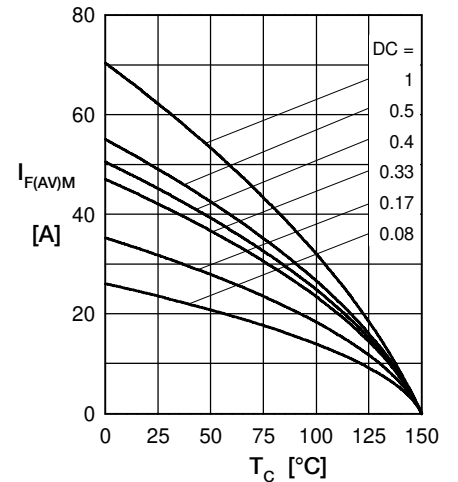


Fig. 5 Max. forward current vs. case temperature per diode

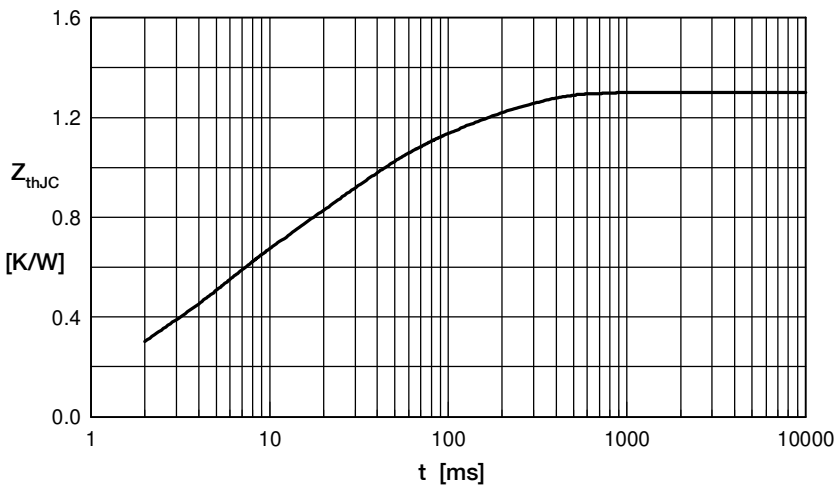


Fig. 6 Transient thermal impedance junction to case vs. time per diode

Constants for  $Z_{thJC}$  calculation:

i	$R_{th}$ (K/W)	$t_i$ (s)
1	0.06070	0.008
2	0.173	0.05
3	0.3005	0.06
4	0.463	0.3
5	0.3028	0.15

## Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

 [View VU052-12NO1 on WIN SOURCE](#)

 [IXYS Information](#)

## Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management